

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

31.03.2026

WURTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	337		2		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		4		
		70	L2			
C-RaS-FR4-DS-1.575mm-070+070-TG150-HF...	50203150	1435		5	A00	B00
		70	L3			
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	337		6		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		7		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		8		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9		

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2285 µm

Version 1.2.20.35

© Würth Elektronik